

Network Infrastructure Challenges

The Switching Silicon Perspective



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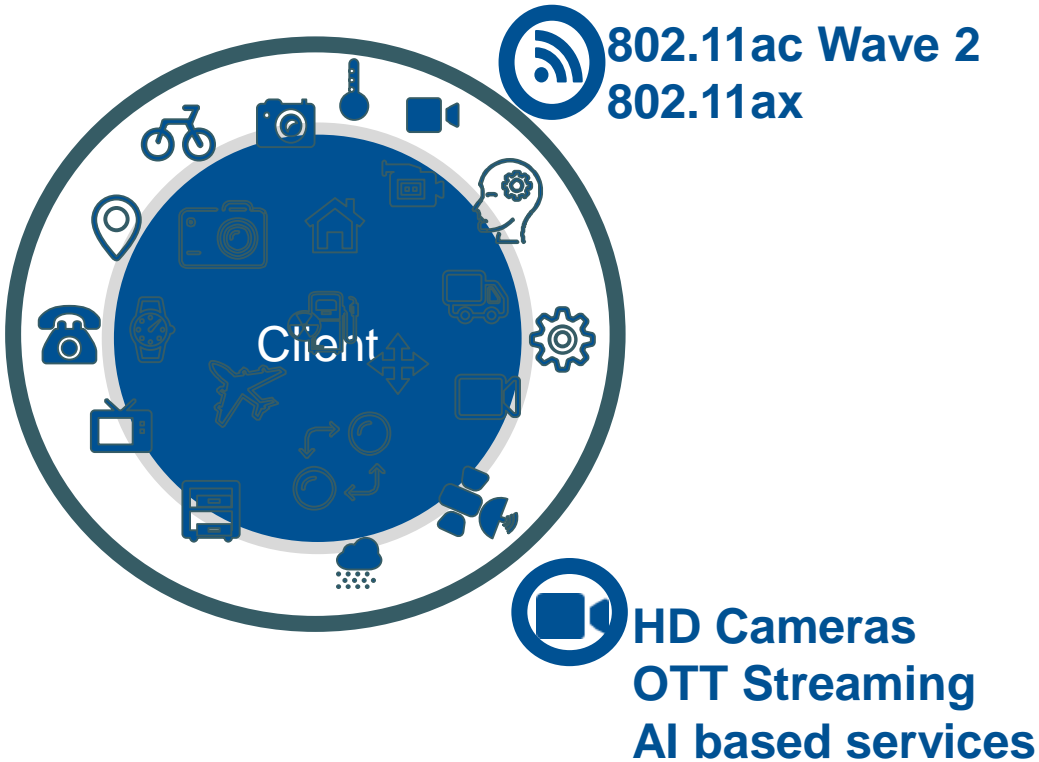
We will talk about

- The change in the network infrastructure
- The challenges
 - As seen by a switching silicon vendor
- Study some of the missing technologies

Network Infrastructure



Client



More end-nodes/services

- More IP's
- More management overhead
- More bandwidth to/from clients
- Lower latency

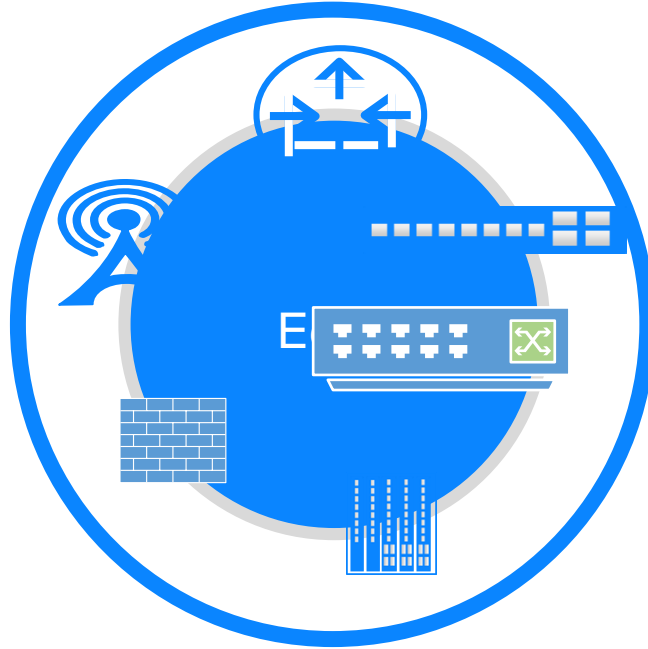
Cloud

- More throughput
- Lossless Ethernet
- Tight management / Analytics
- Low power
- Programmability



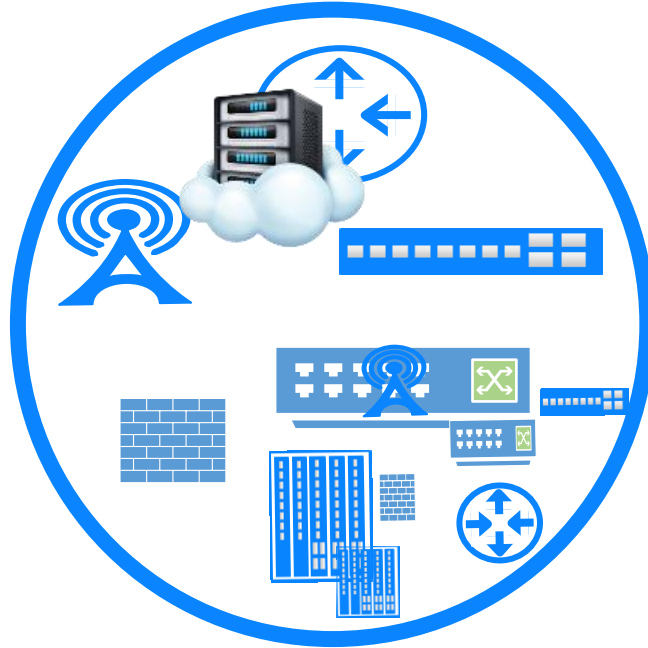
Edge Infrastructure

- More throughput
- Strict latency/jitter guarantees

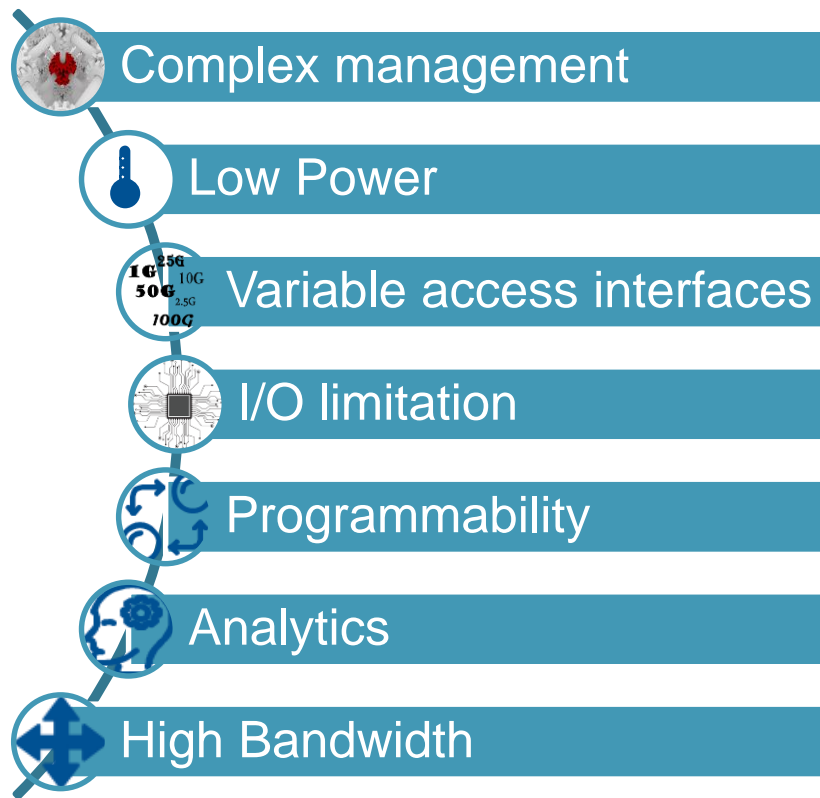


Edge Data Centers

- Tunneling
- NAT
- Throughput
- Low latency



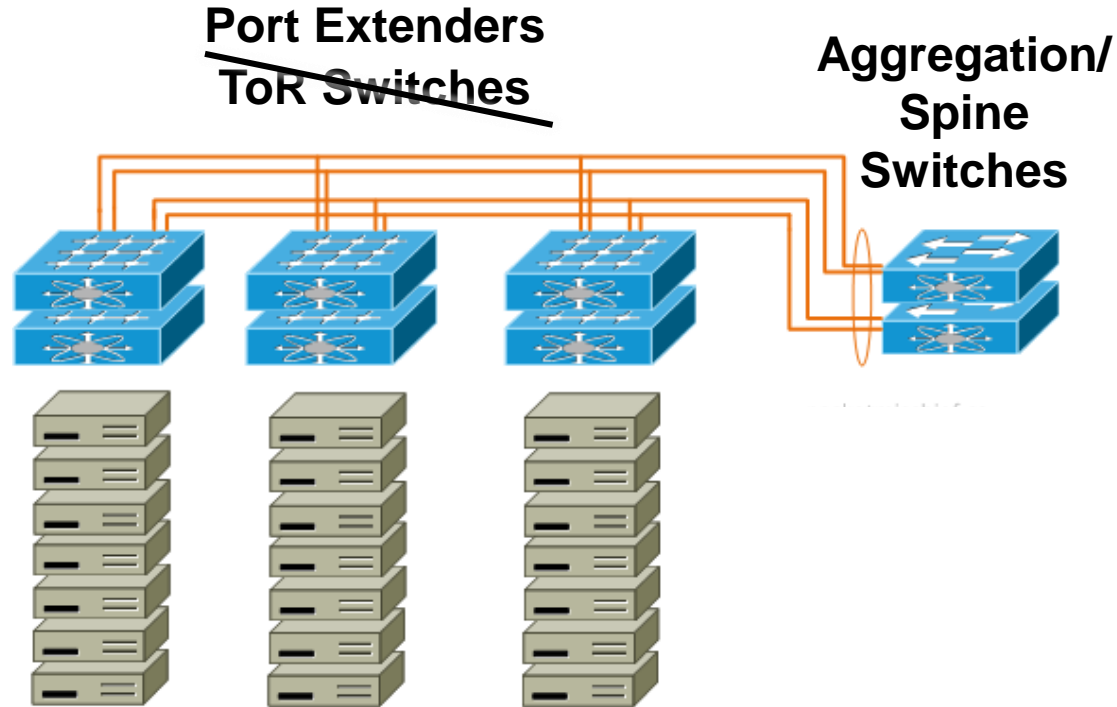
Challenges



System Level Modularity

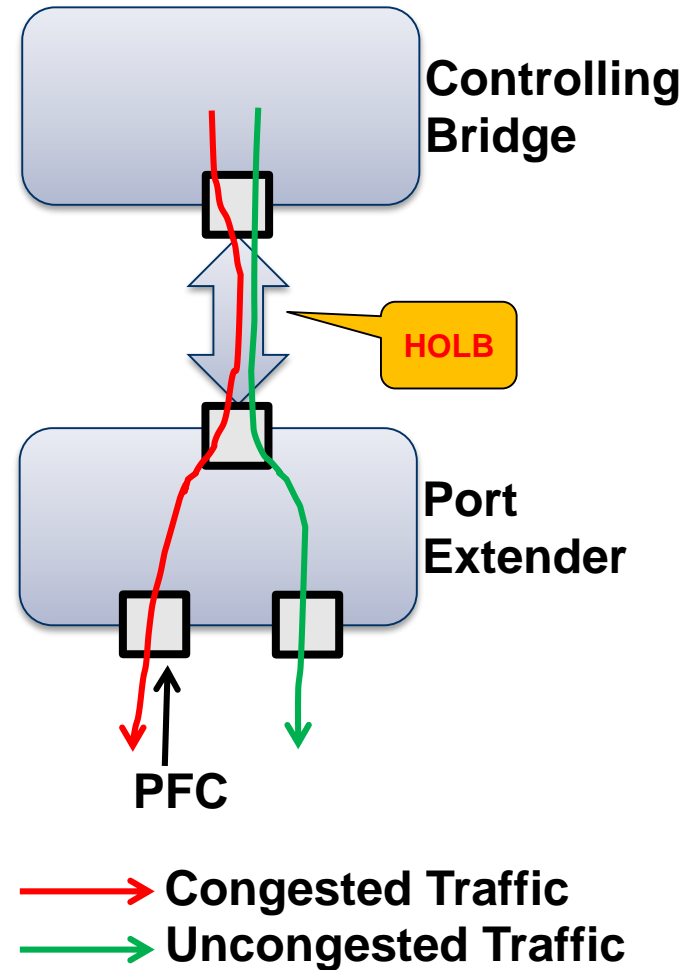
- Simpler management
- Port extender \$ < Switch \$
- Port extender W < Switch W
- Plug & play among vendors

- Addressed by 802.1BR and 802.1Qbg



System Level Modularity

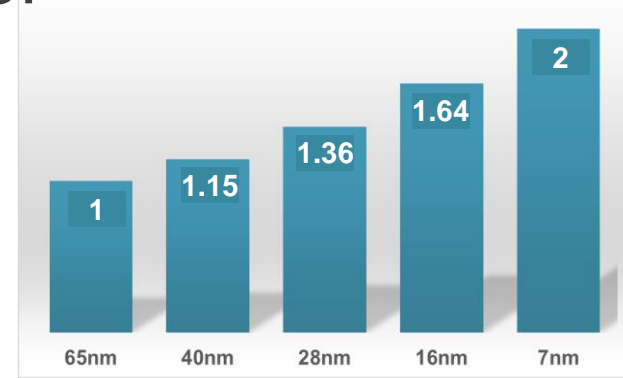
- Has the work been completed by 802.1BR/802.1Qbg?
- Centralized congestion avoidance and transmission selection
 - Reduce PE cost by reducing PE buffer size
 - Small buffer → PE can't be a congestion point → Congestion should be handled by the CB
 - How would the PE signal congestion to the CB?
 - 802.3x and PFC are blocking
- Time for standard inband channelized flow control over Ethernet?



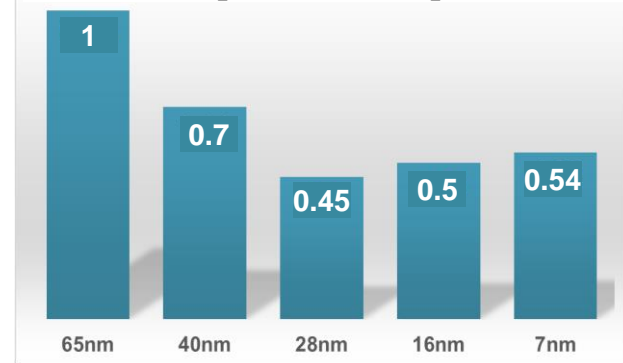
Semiconductor Reality Take #1: Silicon Is More Complex Than Ever

- Process cost
- High investment
- Analog IP
- Many and sometimes conflicting requirements

Si NRE per sqmm
[Normalized]

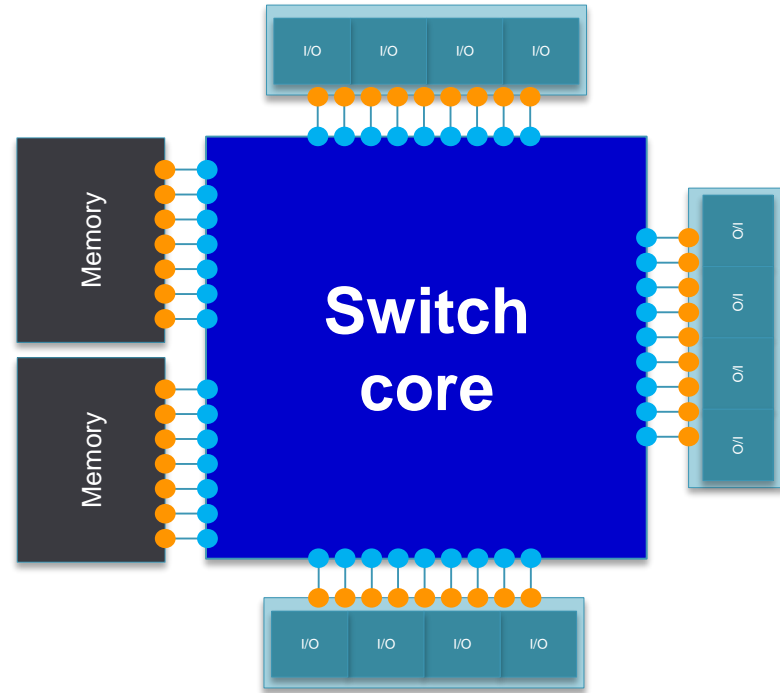


Si Cost Per Gate
[Normalized]



Modularity at the Silicon Level

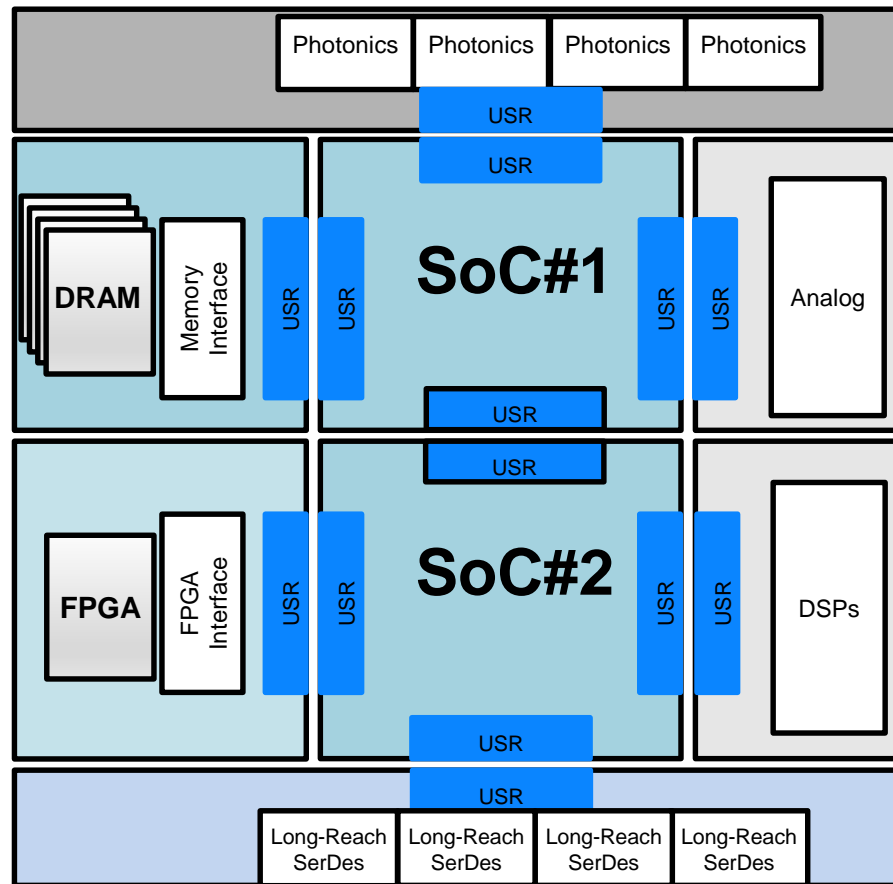
- Separate the I/O from the Main Die
- Separate Serdes Process from Packet Processor Process
- Ability to mix and match processes
- Ability to mix and match FAB Technology





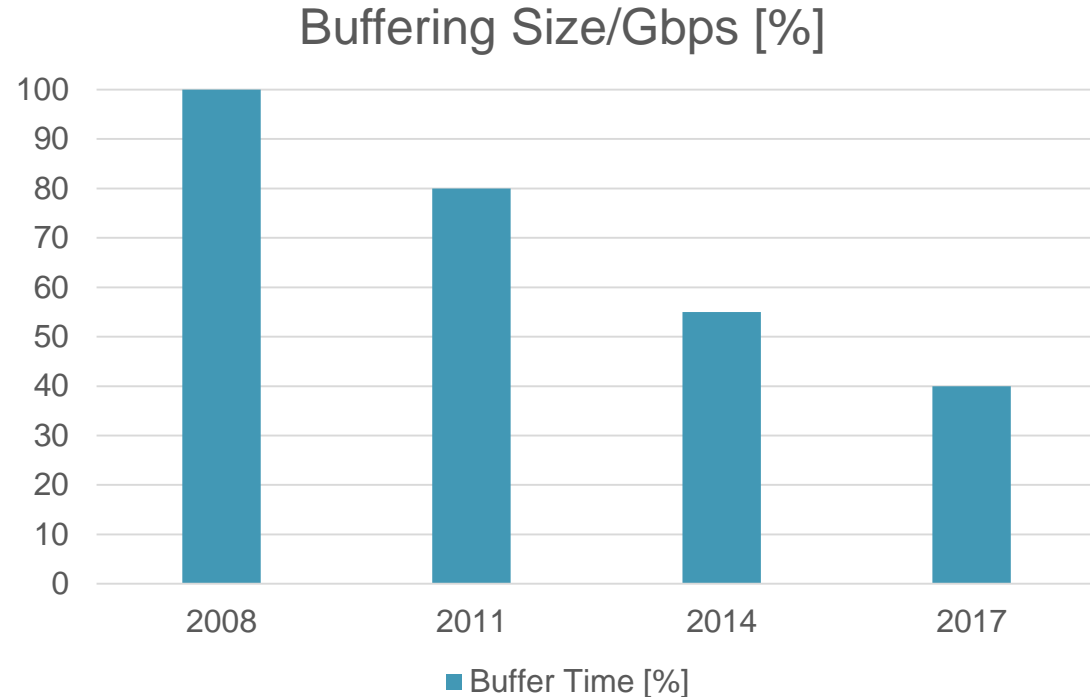
USR ALLIANCE

- USR – Ultra Short Reach Link
- Up to 500Gbps of throughput with low power and small footprint
- Designed for organic substrate and standard MCM package
- Working toward standardization of the USR interface
- Join the Alliance: www.usr-alliance.org



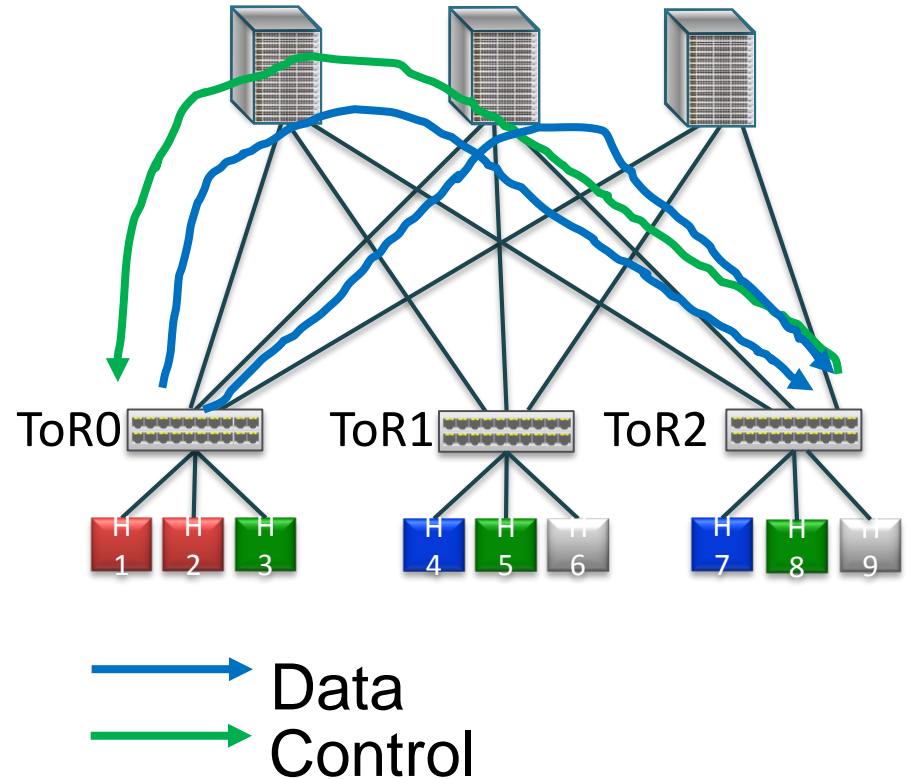
Semiconductor Reality Take #2: Switch Packet Buffer Trends (DCN Switches)

- What happens?
 - Switch throughput scale >> Si technology shrink
- Challenges
 - High throughput
 - Short average FCT
 - Lossless operation



Throughput: Dynamic Load Balancing

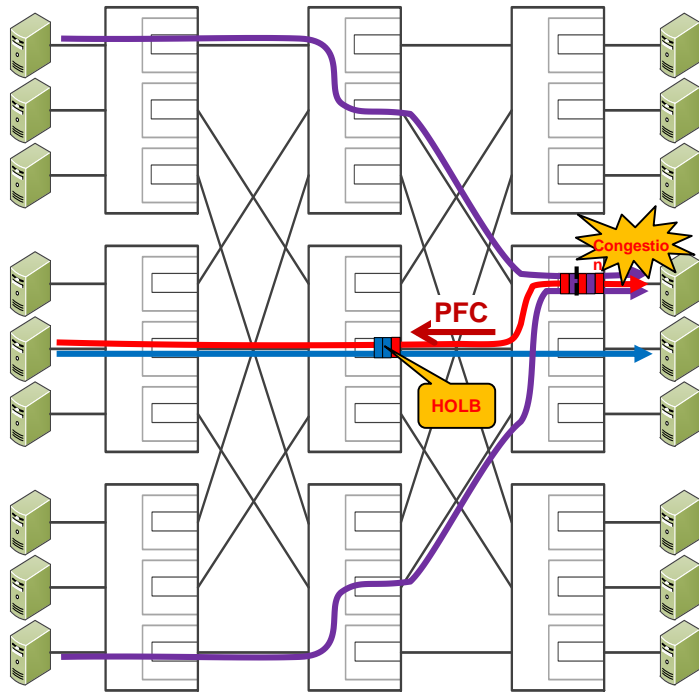
- Many ideas
 - Flow based
 - Flowlet based
 - Packet based
- Some are implemented...
- But all are proprietary/
not interoperable
 - Congestion sensing
 - Congestion signaling
 - Load balancing policy
 - Capability exchange



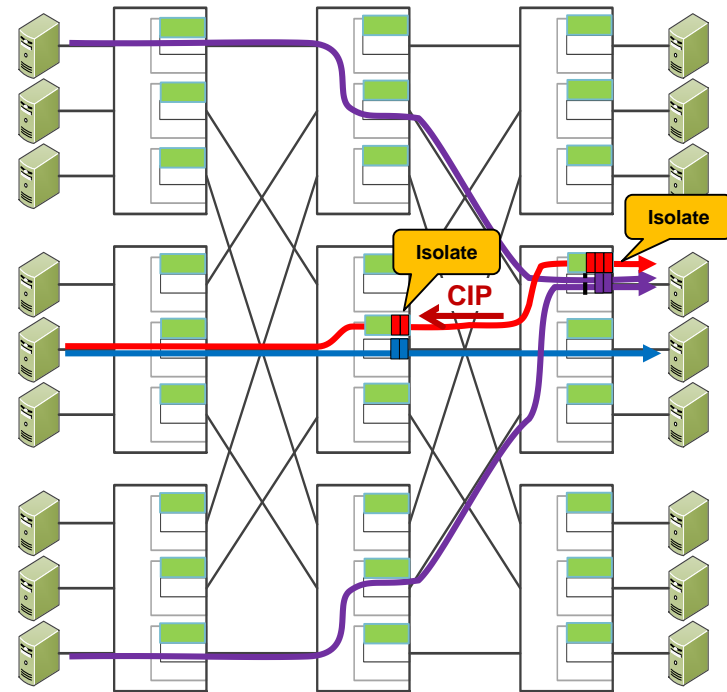
Short FCT in Lossless Networks: Congestion Isolation



Today – Without Congestion Isolation



Congestion Isolation



Summary

- Network infrastructure is evolving and introducing new challenges
- System/Si modularity is driven by requirements for
 - High throughput +
 - Low cost/power +
 - Simpler management
- Sophisticated congestion avoidance/control is driven by
 - Reduced buffering time in switches
- State-of-art is proprietary



Thank you for listening

This is the time for questions 😊



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